

Single Mode Pulsed Laser Diode SCW Series

1310nm, 1550nm and 1625nm Wavelengths Pulsed Laser Diodes

Advanced Photonix's High Power SCW laser modules are designed to meet the performance demands of the optical test equipment. The high peak optical power of SCW Series serve 1310nm through 1625nm wavelengths and are available in fully hermetically sealed packages.

Applications

Photon Counting

Spectroscopy

OTDR Instruments

Optical and LOS Sensors

Talk Sets

Features

300mW and 350mW Optical Power (Pulsed) RoHS Compliant

Warning: Diode laser emissions can be hazardous to eyesight. Standard aversion responses, such as blinking or turning away, are insufficient protection against the potential radiation risks of these devices. Do not directly view the laser aperture during operation. Lasers at 1310nm are classified as IEC Class 3R, while lasers with higher wavelengths fall under Class 1 when used within their specified conditions.

PASSION FOR PHOTONICS DS SCW 1X37-XX0R Rev. B





Absolute Maximum Ratings at $T_A = 25 \text{ °C}$

Parameter	Symbol	Min	Мах	Unit			
Operating Temperature Range	T _{op}	-30	70	°C			
Storage Temperature Range	T _{stg}	-40	85	°C			
Forward Current	I _F	-	1000	mA			
Package	TO56						

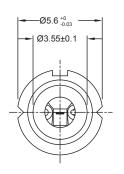
Typical Electro-Optical Specifications at $T_A=25^{\circ}C$, PW = 10µs, D/C=1%

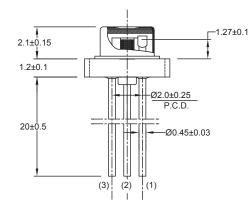
Parameter	Symbol	SCW 1337-350R		SCW 1537-300R		SCW 1637-250R		Unit			
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Optical Power	Р	350	-	-	300	-	-	250	-	-	mW
Threshold Current	I _{TH}	-	30	-	-	35	-	-	45	-	mA
Forward Voltage	V _F	-	3	-	-	3	-	-	3	-	V
Center Wavelength	λ	-	1310	-	-	1550	-	-	1625	-	nm
Spectral Width	Δλ	-	-	8	-	-	10	-	-	12	nm

Reliability data available upon request

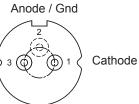
Mechanical Specification

Units are in mm





No Connection





General Care and Handling Instructions

Photodiodes:

Handling and Storage

- Handle Photodiodes gently to prevent damage.
- Avoid exposing Photodiodes to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 Gently clean the glass (borosilicate or quartz window) using a 50/50 mixture of Methanol and isopropyl alcohol and a soft, optical-grade pad.

Special Considerations for Plastic or Epoxy Encapsulated Photodiodes

- Protect from intense light sources such as direct sunlight. Avoid exposure to harsh chemicals like THINNERS, ACETONE,
- and TRICHLOROETHYLENE.
- Cleaning with a 50/50 mixture of Methanol and isopropyl alcohol (IPA) is recommended. Cleaning in an ultrasonic bath is generally not recommended.

CdS Photocells:

Handling and Storage

- Handle CdS Photocells gently to prevent damage.
- Avoid exposing CdS Photocells to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

- Gently clean the glass or plastic covering using a 50/50
- mixture of Methanol and isopropyl alcohol and a soft, opticalgrade pad.

Special Considerations

 DO NOT use Vapor Phase Soldering or Reflow Soldering for CdS components.

Optocouplers and LEDs:

Handling and Storage

- Handle Optocouplers and LEDs gently to prevent damage.
 Avoid exposing the devices to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 For plastic molded devices, cleaning with a 50/50 mixture of Methanol and isopropyl alcohol is recommended. Cleaning in an ultrasonic bath is generally not recommended.

Special Considerations

Avoid exposing plastic molded devices or epoxy glob top devices to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.

Legal Disclaimer

Information in this data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice.



Electrostatic Discharge (ESD) Sensitivity:

All devices are considered ESD-sensitive. They are shipped in ESD protective packaging. When unpacking and using these products, anti-ESD precautions should be observed.

Lead Trimming and Bending:

Standard lead trimming after soldering is an acceptable practice; however, do not attempt to bend or modify the leads incorrectly, as it can damage the glass feed-through or the plastic encapsulant.

Soldering Instructions:

- Use a soldering iron with a tip temperature of 300°C max.
- Consult with your preferred solder manufacturer to determine a solder alloy and flux combination, as well as the reflow profile appropriate for your application.

General Precautions for all Devices

1. Moisture Prevention:

Ensure devices are stored in a dry environment to prevent moisture ingress, which can cause damage during soldering. Refer to J-STD-20 for guidance on proper baking procedures to prevent moisture related damage.

2. Lead Splaying:

If required, carefully splay the leads of the devices according to the specific application needs. Be cautious when splaying leads, as improper techniques may damage the device. Consult technical support or device datasheets for guidance on lead splaying.

3. Mechanical Stress:

Handle devices with care throughout the installation process to prevent damage.

4. Circuit Protection and Layout:

Optimize the circuit design and layout to ensure proper functioning and prevent damage to the devices. Include appropriate protection measures like ESD protection diodes, current-limiting resistors, and voltage regulation.

5. After-Sale Support:

For troubleshooting and device-specific inquiries, please consult with our technical support team. They can offer valuable guidance and suggestions on handling, operation, and application-related questions. To reach them, please contact the Advanced Photonix Applications group at Techsupport@advancedphotonix.com.